	7	6	5	4	3	2	1	
	NOTES: UNLESS OTHERWISE SPECIFIED  1 Rohs Compliant Assembly Required. Assemble per IPC—A— 2 AQUEOUS BASED CLEANING AFTER SOLDER FOR ALL COMPONEI Rohs SOLDER PROCESS IS ACCEPTABLE.  3 ITEM IDENTIFICATION: MARK REVISION NUMBER OF THIS DRAWING	NTS IS PREFERRED, NO—CLEAN				REV DESCRIPTION  O1 INITIAL RELEASE  O2 ALPHA 2 RELEASE	REVISIONS  DATE APRVD  08/11/2016  09/19/2016	
							D	
C								
В				J4_6 J4_8 J4_10 J4_12 J4_14 J4_16 J4_18 J4_20 J4_22 J4_24 J4_26 J4_28				B
				ASSEMBLY TOP				
					DIMENSIONS ARE	D. BRUEY / M. CIUFFO  MECH ENG	Ave. Suite 300, Seattle, WA 98101 206.381.0898  RINTED CIRCUIT BOARD ASSEMBLY  Sensor Breakout A	<b>\</b>
						SIZE DWG NO	600—100861 02 SHEET 1 OF 2	
	7	6		4			1	

